Sequence-Pair　　　　　　　　　　　　　　　= Two-layer floorplanning based on sequence-pair representation

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(physical design)　　　　　　　　(floorplanning)

2D　　　　　　　　　　　　　　　　　　　System-On-a-Chip (SoC)

3D

2D

Sequence-Pair　　　　　　　　[4]　　　　　(simulated annealing)

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